

# DATA SHEET

## SURFACE-MOUNT CERAMIC MULTILAYER CAPACITORS

High-voltage SC type: NP0/X7R

X1/Y2 & X2

10pF to 56nF



## SCOPE

This specification describes safety certification NP0/X7R series chip capacitors with lead-free terminations.

## APPLICATIONS

- PCs, Notebook
- Networking
- Power supplies

## FEATURES

- Supplied in tape on reel
- Nickel-barrier end termination
- RoHS compliant
- Halogen Free compliant

## MARKING

- YSC: Safety Cap
- YST: Safety Cap with Soft-Termination



## ORDERING INFORMATION - GLOBAL PART NUMBER, PHYCOMP CTC & I2NC

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value.

### YAGEO BRAND ordering codes

#### GLOBAL PART NUMBER (PREFERRED)

**XX** **XXXX** **X** **X** **XXX** **X** **B** **X** **XXX**  
 (1) (2) (3) (4) (5) (6) (7) (8)

#### (1) SERIES

SC : Safety Capacitor

ST : Safety Capacitor with Soft-Termination

#### (2) SIZE – INCH BASED (METRIC)

1808 (4520)

2211 (5728)

2220 (5750)

#### (3) TOLERANCE

J =  $\pm 5\%$

K =  $\pm 10\%$

M =  $\pm 20\%$

#### (4) PACKING STYLE

K = Blister taping reel; Reel 7 inch

#### (5) TC MATERIAL

NPO

X7R

#### (6) IMPULSE VOLTAGE

W = X1/Y2 Series for TUV/UL

T = X2 Series for TUV/UL

#### (7) PROCESS

N = NPO

B = Class 2 product

#### (8) CAPACITANCE VALUE

2 significant digits+number of zeros

The 3rd digit signifies the multiplying factor, and letter R is decimal point

Example: 121 =  $12 \times 10^1 = 120 \text{ pF}$

## CONSTRUCTION

The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two end terminations and finally covered with a layer of plated tin (NiSn). The terminations are lead-free. A cross section of the structure is shown in Fig.1.

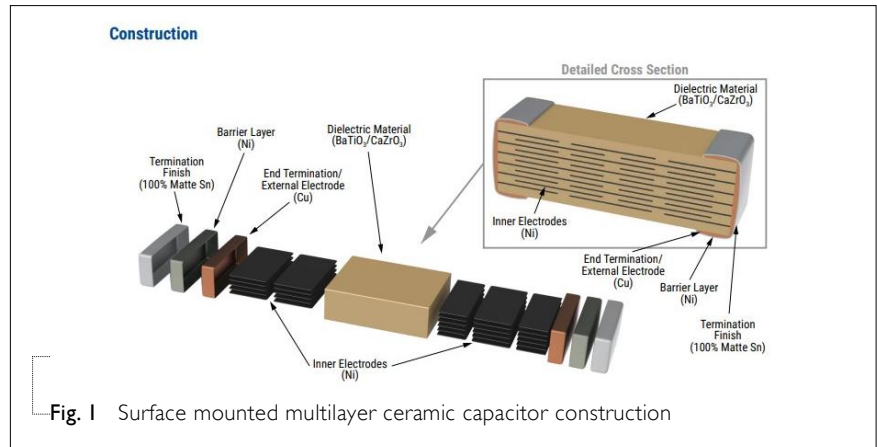


Fig. 1 Surface mounted multilayer ceramic capacitor construction

## DIMENSION

Table I For outlines see fig. 2

TYPE	L1 (MM)	W (MM)	T (MM)	L2 / L3(MM)		L4(MM)	DIMENSION CODE
				MIN.	MAX.	MIN.	
1808	4.5+0.6/-0.3	2.0 ±0.30	1.25 ±0.20	0.25	0.40	4.0	HA
	4.5+0.6/-0.3	2.0 ±0.30	1.6 ±0.20	0.25	0.40	4.0	HC
	4.5+0.6/-0.3	2.0 ±0.30	2.0 ±0.20	0.25	0.40	4.0	HD
	4.5+0.9/-0.3	2.0 ±0.40	1.25 ±0.20	0.25	0.40	4.0	HE
	4.5+0.9/-0.3	2.0 ±0.40	1.6 ±0.20	0.25	0.40	4.0	HG
	4.5+0.9/-0.3	2.0 ±0.40	2.0 ±0.20	0.25	0.40	4.0	HI
2211	5.7 ±0.40	2.8 ±0.30	1.6 ±0.20	0.3	0.75	4.0	GA
	5.7 ±0.40	2.8 ±0.30	2.0 ±0.20	0.3	0.75	4.0	GB
	5.7 ±0.40	2.8 ±0.30	2.5 ±0.30	0.3	0.75	4.0	GC
	5.7 ±0.40	2.8 ±0.30	2.8 ±0.30	0.3	0.75	4.0	GD
	5.7 ±0.50	2.8 ±0.40	1.6 ±0.20	0.3	0.75	4.0	GE
	5.7 ±0.50	2.8 ±0.40	2.0 ±0.20	0.3	0.75	4.0	GF
	5.7 ±0.50	2.8 ±0.40	2.5 ±0.30	0.3	0.75	4.0	GG
	5.7 ±0.50	2.8 ±0.40	2.8 ±0.30	0.3	0.75	4.0	GH
2220	5.7 ±0.40	5.0 ±0.40	2.0 ±0.20	0.3	0.75	4.0	KB
	5.7 ±0.40	5.0 ±0.40	2.5 ±0.30	0.3	0.75	4.0	KC
	5.7 ±0.40	5.0 ±0.40	2.8 ±0.30	0.3	0.75	4.0	KD
	5.7 ±0.50	5.0 ±0.40	2.0 ±0.20	0.3	0.75	4.0	KF
	5.7 ±0.50	5.0 ±0.40	2.5 ±0.30	0.3	0.75	4.0	KG
	5.7 ±0.50	5.0 ±0.40	2.8 ±0.30	0.3	0.75	4.0	KH

## OUTLINES

For dimension see Table I

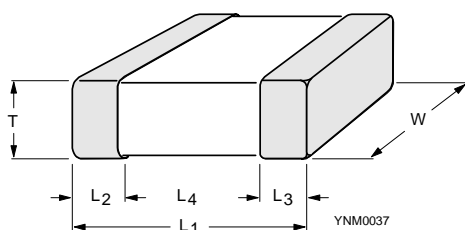


Fig. 2 Surface mounted multilayer ceramic capacitor dimension

CAPACITANCE RANGE & THICKNESS FOR NP0 X1/Y2

Table 2 Sizes from 1808

CAP.	SC 1808, NP0 X1/Y2	ST 1808, NP0 X1/Y2
10 PF	HA	HE
12 PF	HA	HE
15 PF	HA	HE
18 PF	HA	HE
22 PF	HA	HE
27 PF	HC	HG
33 PF	HC	HG
39 PF	HC	HG
47 PF	HC	HG
56 PF	HC	HG
68 PF	HC	HG
82 PF	HC	HG
100 PF	HD	HI
120 PF	HD	HI
150 PF	HD	HI
180 PF	HD	HI
220 PF	HD	HI
270 PF	HD	HI
330 PF	HD	HI
390 PF		
470 PF		

Table 3

CASE SIZE	L (MM)	W (MM)	T (MM)	DIMENSION CODE
1808	4.5+0.6/-0.3	2.0 ±0.30	1.25 ±0.20	HA
	4.5+0.6/-0.3	2.0 ±0.30	1.6 ±0.20	HC
	4.5+0.6/-0.3	2.0 ±0.30	2.0 ±0.20	HD
	4.5+0.9/-0.3	2.0 ±0.40	1.25 ±0.20	HE
	4.5+0.9/-0.3	2.0 ±0.40	1.6 ±0.20	HG
	4.5+0.9/-0.3	2.0 ±0.40	2.0 ±0.20	HI

CAPACITANCE RANGE & THICKNESS FOR X7R X1/Y2 AND X2

Table 4 Sizes from 1808 to 2220

CAP.	SC 1808, X7R X1/Y2	ST 1808, X7R X1/Y2	SC 2211, X7R X1/Y2	ST 2211, X7R X1/Y2	SC 2220, X7R X1/Y2	ST 2220, X7R X2 X1/Y2	X2
100 PF	HC	HG	GA	GE	KB	KF	
120 PF	HC	HG	GA	GE	KB	KF	
150 PF	HC	HG	GA	GE	KB	KF	
180 PF	HC	HG	GA	GE	KB	KF	
220 PF	HC	HG	GA	GE	KB	KF	
270 PF	HD	HI	GA	GE	KB	KF	
330 PF	HD	HI	GA	GE	KB	KF	
390 PF	HD	HI	GA	GE	KB	KF	
470 PF	HD	HI	GB	GF	KB	KF	
560 PF	HD	HI	GB	GF	KB	KF	
680 PF	HD	HI	GB	GF	KB	KF	
820 PF	HD	HI	GB	GF	KB	KF	
1.0 NF	HD	HI	GC	GG	KB	KF	
1.2 NF			GC	GG	KC	KG	
1.5 NF			GC	GG	KC	KG	
1.8 NF			GC	GG	KC	KG	
2.2 NF			GC	GG	KC	KG	
2.7 NF			GD	GH	KC	KG	
3.3 NF					KC	KG	
3.9 NF					KC	KG	
4.7 NF					KC	KG	
5.6 NF							
6.8 NF							
8.2 NF							
10 NF						KC	KG
12 NF						KC	KG
15 NF						KC	KG
18 NF						KC	KG
22 NF						KD	KH
27 NF						KD	KH
33 NF						KD	KH
39 NF						KD	KH
47 NF						KD	KH
56 NF						KD	KH

Table 5

CASE SIZE	L (MM)	W (MM)	T (MM)	DIMENSION CODE
1808	4.5+0.6/-0.3	2.0 ±0.30	1.25 ±0.20	HA
	4.5+0.6/-0.3	2.0 ±0.30	1.6 ±0.20	HC
	4.5+0.6/-0.3	2.0 ±0.30	2.0 ±0.20	HD
	4.5+0.9/-0.3	2.0 ±0.40	1.25 ±0.20	HE
	4.5+0.9/-0.3	2.0 ±0.40	1.6 ±0.20	HG
	4.5+0.9/-0.3	2.0 ±0.40	2.0 ±0.20	HI
2211	5.7 ±0.40	2.8 ±0.30	1.6 ±0.20	GA
	5.7 ±0.40	2.8 ±0.30	2.0 ±0.20	GB
	5.7 ±0.40	2.8 ±0.30	2.5 ±0.30	GC
	5.7 ±0.40	2.8 ±0.30	2.8 ±0.30	GD
	5.7 ±0.50	2.8 ±0.40	1.6 ±0.20	GE
	5.7 ±0.50	2.8 ±0.40	2.0 ±0.20	GF
	5.7 ±0.50	2.8 ±0.40	2.5 ±0.30	GG
	5.7 ±0.50	2.8 ±0.40	2.8 ±0.30	GH
2220	5.7 ±0.40	5.0 ±0.40	2.0 ±0.20	KB
	5.7 ±0.40	5.0 ±0.40	2.5 ±0.30	KC
	5.7 ±0.40	5.0 ±0.40	2.8 ±0.30	KD
	5.7 ±0.50	5.0 ±0.40	2.0 ±0.20	KF
	5.7 ±0.50	5.0 ±0.40	2.5 ±0.30	KG
	5.7 ±0.50	5.0 ±0.40	2.8 ±0.30	KH

THICKNESS CLASSES AND PACKING QUANTITY

Table 6

DESCRIPTION	SIZE CODE	THICKNESS CLASSIFICATION (mm)	12 mm TAPE WIDTH /AMOUNT PER REEL Ø180 mm, 7" Blister
Safety Certification Capacitor	1808	1.25 ±0.20	3,000
		1.6 ±0.20	2,000
		2.0 ±0.20	2,000
	2211	1.6 ±0.20	1,000
		2.0 ±0.20	1,000
		2.5 ±0.30	500
		2.8 ±0.30	500
	2220	2.0 ±0.20	1,000
		2.5 ±0.30	500
		2.8 ±0.30	500

ELECTRICAL CHARACTERISTICS**NP0/X7R DIELECTRIC CAPACITORS; NISN TERMINATIONS**

Unless otherwise stated all electrical values apply at an ambient temperature of  $20 \pm 1$  °C, an atmospheric pressure of 86 to 106 kPa, and a relative humidity of 63 to 67%.

Table 7

DESCRIPTION		VALUE
Capacitance range		10pF to 56nF
Capacitance tolerance		
NP0	C < 10 pF	$\pm 0.25$ pF, $\pm 0.5$ pF
	C $\geq$ 10 pF	$\pm 5\%$
X7R		$\pm 10\%$
Dissipation factor (D.F.)		
NP0	C < 30 pF	$\leq 1 / (400 + 20C)$
	C $\geq$ 30 pF	$\leq 0.1\%$
X7R		$\leq 2.5\%$
Insulation resistance after 1 minute at $U_r$ (DC)		$R_{ins} \geq 10 \text{ G}\Omega$ or $R_{ins} \times C \geq 500$ seconds whichever is less
Maximum capacitance change as a function of temperature (temperature characteristic/coefficient):		
NP0		$\pm 30$ ppm/°C
X7R		$\pm 15\%$
Operating temperature range:		
NP0/X7R		$-55$ °C to $+125$ °C

**CAPACITOR REQUIREMENT**

Table 8

SAFETY RATING	VOLTAGE RATING	WITHSTANDING VOLTAGE	IMPULSE VOLTAGE
X1	250 VAC	1,500 VAC	4,000 V
X2	250 VAC	1,500 VAC	2,500 V
Y2	250 VAC	1,500 VAC	5,000 V

SOLDERING RECOMMENDATION

Table 9

SOLDERING METHOD	SIZE				
	0402	0603	0805	1206	$\geq 1210$
Reflow	$\geq 0.1 \mu\text{F}$	$\geq 1.0 \mu\text{F}$	$\geq 2.2 \mu\text{F}$	$\geq 4.7 \mu\text{F}$	Reflow only
Reflow/Wave	$< 0.1 \mu\text{F}$	$< 1.0 \mu\text{F}$	$< 2.2 \mu\text{F}$	$< 4.7 \mu\text{F}$	---

TESTS AND REQUIREMENTS

Table 10 Test procedures and requirements

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Mounting	IEC 60384-21/22	4.3 The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage
Visual Inspection and Dimension Check		4.4 Any applicable method using × 10 magnification	In accordance with specification
Capacitance		4.5.1 NP0: f = 1 MHz for C ≤ 1 nF, measuring at voltage 1 V <sub>rms</sub> at 20 °C; f = 1 KHz for C > 1 nF, measuring at voltage 1 V <sub>rms</sub> at 20 °C X7R: f = 1 KHz for C ≤ 10 µF, measuring at voltage 1 V <sub>rms</sub> at 20 °C	Within specified tolerance
Dissipation Factor (D.F.)		4.5.2 NP0: f = 1 MHz for C ≤ 1 nF, measuring at voltage 1 V <sub>rms</sub> at 20 °C; f = 1 KHz for C > 1 nF, measuring at voltage 1 V <sub>rms</sub> at 20 °C X7R: f = 1 KHz for C ≤ 10 µF, measuring at voltage 1 V <sub>rms</sub> at 20 °C	In accordance with specification
Insulation Resistance		4.5.3 To apply 500 V max for 60 seconds	In accordance with specification

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS												
Temperature Characteristic	4.6	<p>Capacitance shall be measured by the steps shown in the following table.</p> <p>The capacitance change should be measured after 5 min at each specified temperature stage.</p> <table><tr><th>Step</th><th>Temperature(°C)</th></tr><tr><td>a</td><td>25±2</td></tr><tr><td>b</td><td>Lower temperature±3°C</td></tr><tr><td>c</td><td>25±2</td></tr><tr><td>d</td><td>Upper Temperature±2°C</td></tr><tr><td>e</td><td>25±2</td></tr></table> <p>(1) Class I</p> <p>Temperature Coefficient shall be calculated from the formula as below</p> $\text{Temp, Coefficient} = \frac{C2 - C1}{C1 \times \Delta T} \times 10^6 \text{ [ppm/°C]}$ <p>C1: Capacitance at step c C2: Capacitance at 125°C ΔT: 100°C (=125°C -25°C)</p> <p>(2) Class II</p> <p>Capacitance Change shall be calculated from the formula as below</p> $\Delta C = \frac{C2 - C1}{C1} \times 100\%$ <p>C1: Capacitance at step c C2: Capacitance at step b or d</p>	Step	Temperature(°C)	a	25±2	b	Lower temperature±3°C	c	25±2	d	Upper Temperature±2°C	e	25±2	<p>Class I: Δ C/C: ±30ppm</p> <p>Class2: X7R: Δ C/C: ±15%</p>
Step	Temperature(°C)														
a	25±2														
b	Lower temperature±3°C														
c	25±2														
d	Upper Temperature±2°C														
e	25±2														
Adhesion	4.15	<p>a. A force applied for 10 seconds to the line joining the terminations and in a plane parallel to the substrate for size ≥ 0603 : a force of 5N applied</p> <p>b. A force applied until broken For size ≥ 0603: ≥ 5N</p>	No visible damage												
Bond Strength of Plating on End Face	IEC 60384-21/22 4.8	<p>Mounting in accordance with IEC 60384-22 paragraph 4.3</p> <p>Conditions: bending 1 mm at a rate of 1 mm/s, radius jig 340 mm</p>	<p>No visible damage</p> <p>ΔC/C</p> <p>NP0: ≤ 1% or 0.5 pF whichever is greater</p> <p>X7R: ≤ 10%</p>												
Resistance to Soldering Heat	4.9	<p>Precondition: 150 +0/-10 °C for 1 hour, then keep for 24 ±1 hours at room temperature</p> <p>Preheating: for size ≤ 1206: 120 °C to 150 °C for 1 minute</p> <p>Preheating: for size &gt;1206: 100 °C to 120 °C for 1 minute and 170 °C to 200 °C for 1 minute</p> <p>Solder bath temperature: 260 ±5 °C</p> <p>Dipping time: 10 ±0.5 seconds</p> <p>Recovery time: 24 ±2 hours</p>	<p>The termination shall be well tinned</p> <p>ΔC/C</p> <p>NP0: ≤ 0.5% or 0.5 pF whichever is greater</p> <p>X7R: ≤ 10%</p> <p>D.F. within initial specified value</p> <p>R<sub>ins</sub> within initial specified value</p>												

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Solderability	4.10	Unmounted chips completely immersed in a solder bath at $235 \pm 5$ °C Dipping time: $2 \pm 0.5$ seconds Depth of immersion: 10 mm	The termination shall be well tinned
Damp Heat with $U_r$ Load	4.13	Initial measurements; after $150 +0/-10$ °C for 1 hour, then keep for $24 \pm 1$ hours at room temperature Duration and conditions: $500 \pm 12$ hours at $40 \pm 2$ °C; 90 to 95% RH; 1.0 $U_r$ applied Final measurement: perform a heat treatment at $150 +0/-10$ °C for 1 hour; final measurements shall be carried out $24 \pm 1$ hours after recovery at room temperature without load	$\Delta C/C$ NP0: $\leq 2\%$ or 1 pF whichever is greater X7R: $\leq 15\%$ D.F. NP0: $\leq 2 \times$ specified value X7R: $\geq 100V: \leq 5\%$ Rins NP0: $\geq 2,500 M\Omega$ or $Rins \times Cr \geq 25s$ whichever is less X7R: $\geq 500 M\Omega$ or $Rins \times Cr \geq 25s$ whichever is less
Endurance	EN132400 4.14 SC	Perform shear test, substrate bending test, impulse voltage and then endurance test progressively  Same as the above except for 1.25 $U_r$ for X-capacitor and 1.7 $U_r$ for Y-capacitor  Once every hour the voltage shall be increased to 1000 VAC for 0.1 s  Total time take to change over to 1000 VAC and back does not exceed 30 s	Visual examination  $DC/C < \pm 20\%$  Voltage proof  $IR > 3 \times 10E9 \Omega$
Impulse Voltage	4.13 SC IEC-60384-14	X1: 4.0 KV, X2: 2.5 KV Y2: 5.0 KV, Y3: None If any three successive impulses are shown by the oscilloscope monitor to have had a waveform indicating that no self-healing breakdowns or flashovers have taken place in the capacitor; then no further impulses shall be applied and the capacitor shall be counted as conforming. 24 impulses have been applied to the capacitor and 3 or more of them are of a waveform indicating that no self-heating breakdowns or flashovers have occurred. Time between impulses shall not be less than 10 s	No breakdown or flashover
Robustness of Termination (Pull Strength)	4.3 SC	a. A force applied for 10 sec to the line joining the terminations and in a plane parallel to the substrate.  b. A force applied until broken	a. No visible damage  b. Force size $\geq 0603: \geq 5N$
Voltage Proof	4.2.1 SC	X capacitor: Applied voltage 1.075K VDC (4.3 $U_r$ ) Y capacitor: Applied voltage 1.5K VAC	No breakdown or flashover

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	May 21, 2024	-	- New datasheet for high voltage NP0/X7R series with lead-free terminations

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